

Amendment to the Specification:

Please amend the paragraph on page 16, line 1 beginning with the word “The” and ending with the word “2m” as follows:

The next steps involve creating features in thinned dielectric layer **212'**. Initially, photoresist is applied to both sides of the existing structure. Phototools are aligned to the metal patterns on each side of the laminate structure and both layers of photoresist are imaged by exposure to suitable radiation and developed in the same manner as previously described. This results in patterned photoresist layers **224** and **226** aligned to circuit traces **220** and etched metal substrate **210**, respectively, as illustrated in **Fig. 2j**. Next, the exposed portions of dielectric layer **[[212]] 212'** are shaped or removed by exposure to, e.g., plasma or chemical etchants, and the remaining portions of photoresist layers **224** and **226** are removed to leave the flexure structure illustrated in **Fig. 2k**. Suitable methods are known to those skilled in the art. Subsequently, another layer, or layers, of photoresist may be applied, imaged and developed, on one or both sides of the structure to allow circuit traces **220** to be plated with an additional layer of conductive material **228** suitable for electrical bonding or contact compatibility, e.g., gold, as illustrated in **Fig. 2l**. Optionally, as a final step, a layer of covercoat **230** may be applied, exposed and developed to form a protective layer over circuit traces **220**, as illustrated in **Fig. 2m**.